

LOW CAPACITANCE TVS ARRAY

APPLICATIONS

- ✓ Wireless Communication Circuits
- ✓ RS-422, RS-432 & RS-485
- ✓ Low Voltage ASICs
- ✓ Ethernet - 10/100 Base T

IEC COMPATIBILITY (EN61000-4)

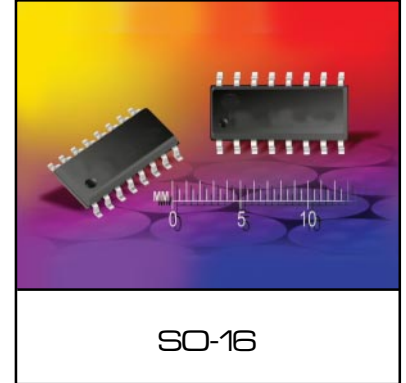
- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns
- ✓ 61000-4-5 (Surge): 12A, 8/20 μ s Level 1 (Line-Ground) & Level 2 (Line-Line)

FEATURES

- ✓ 500 Watts Peak Pulse Power per Line (tp=8/20 μ s)
- ✓ Unidirectional & Bidirectional Configuration
- ✓ ESD Protection > 40 kilovolts
- ✓ Available in Multiple Voltage Types: 3.3V to 36V
- ✓ Protects Up to Eight (8) Lines
- ✓ **LOW CAPACITANCE: 15pF**
- ✓ RoHS Compliant in Lead-Free Versions

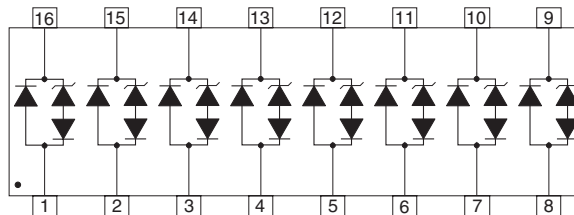
MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SO-16 Package
- ✓ Weight 0.15 grams (Approximate)
- ✓ Available in Tin-Lead or Lead-Free Pure-Tin Plating(Annealed)
- ✓ Solder Reflow Temperature:
 - Tin-Lead - Sn/Pb, 85/15: 240-245°C
 - Pure-Tin - Sn, 100: 260-270°C
- ✓ Flammability rating UL 94V-0
- ✓ 16mm Tape and Reel Per EIA Standard 481
- ✓ Marking: Logo, Part Number, Date Code & Pin One Defined By Dot on Top of Package

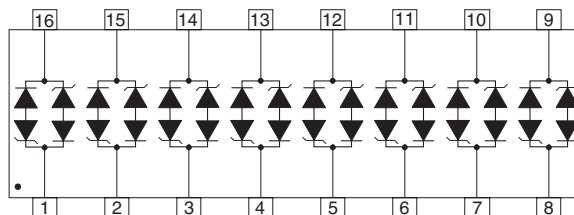


PIN CONFIGURATIONS

UNIDIRECTIONAL CONFIGURATION



BIDIRECTIONAL CONFIGURATION



DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	500	Watts
Operating Temperature	T_J	-55°C to 150°C	°C
Storage Temperature	T_{STG}	-55°C to 150°C	°C
Forward Voltage @ 50mA, 300 μs - Square Wave (Note 1)	V_F	1.5	Volts
Soldering Temperature for 10 seconds	T_L	265	°C

Note 1: Only applies to unidirectional devices.

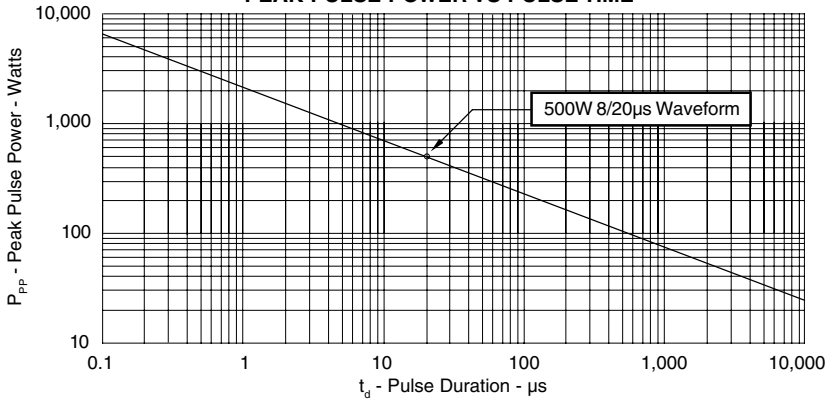
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER (Notes 1 & 2)	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ $I_p = 1 A$ V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ 8/20 μs $V_C @ I_{PP}$	MAXIMUM LEAKAGE CURRENT @ V_{WM} I_D μA	MAXIMUM CAPACITANCE @ 0V, 1 MHz C pF	TEMPERATURE COEFFICIENT OF $V_{(BR)}$ $\theta V_{(BR)}$ mV/°C
SM16LC03	3.3	4.5	7.0	20.0V @ 35A	125	15	-3
SM16LC03C	3.3	4.5	7.0	20.0V @ 35A	125	15	-3
SM16LC05	5.0	6.0	9.8	24.0V @ 42A	20	15	3
SM16LC05C	5.0	6.0	9.8	24.0V @ 42A	20	15	3
SM16LC08	8.0	8.5	13.4	26.0V @ 30A	10	15	9
SM16LC08C	8.0	8.5	13.4	26.0V @ 30A	10	15	9
SM16LC12	12.0	13.3	19.0	33.0V @ 21A	2	15	16
SM16LC12C	12.0	13.3	19.0	33.0V @ 21A	2	15	16
SM16LC15	15.0	16.7	25.5	39.0V @ 15A	2	15	17
SM16LC15C	15.0	16.7	25.5	39.0V @ 15A	2	15	17
SM16LC24	24.0	26.7	40.0	57.0V @ 10A	2	15	26
SM16LC24C	24.0	26.7	40.0	57.0V @ 10A	2	15	26
SM16LC36	36.0	40.0	53.0	72.0V @ 7.0A	2	15	36
SM16LC36C	36.0	40.0	53.0	72.0V @ 7.0A	2	15	36

Note 1: Part numbers with a "C" suffix are bidirectional devices, i.e., SM16LC05C.

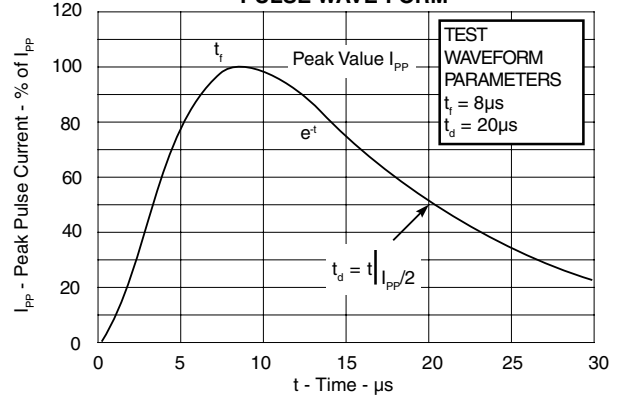
Note 2: *Unidirectional Devices Only:* Do not surge from pins 16 to 1, 15 to 2, 14 to 3, 13 to 4, 12 to 5, 11 to 6, 10 to 7 and 9 to 8. PIV typically greater than 100V for each rectifier diode.

GRAPHS

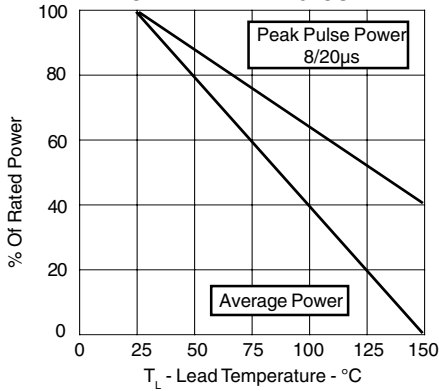
**FIGURE 1
PEAK PULSE POWER VS PULSE TIME**



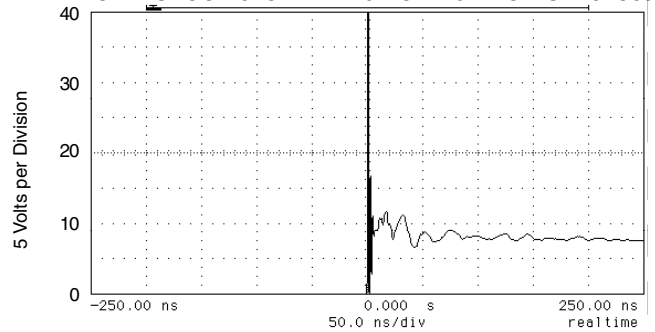
**FIGURE 2
PULSE WAVE FORM**



**FIGURE 3
POWER DERATING CURVE**

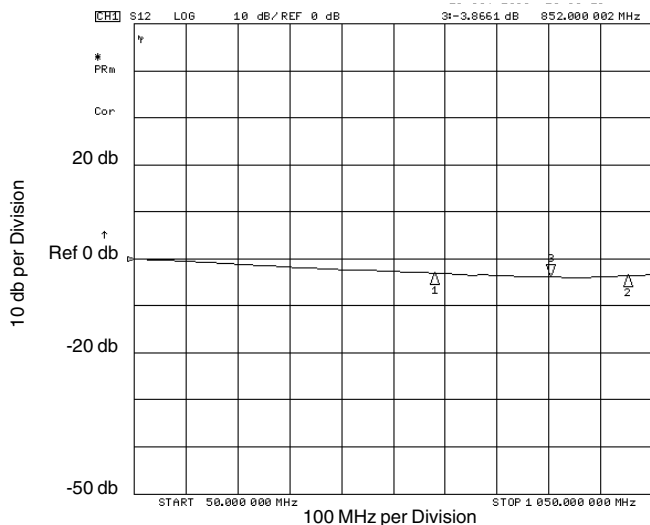


**FIGURE 4
OVERSHOOT & CLAMPING VOLTAGE FOR SM16LC05**

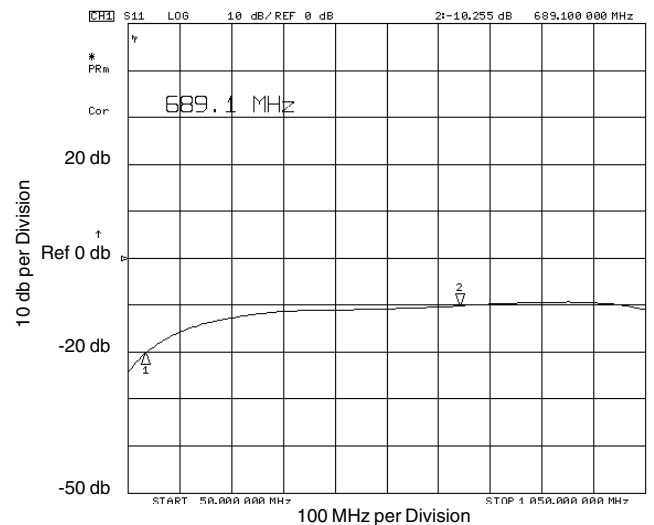


ESD Test Pulse: 25 kilovolt, 1/30ns (waveform)

**FIGURE 5
INSERTION LOSS - SM16LC12**



**FIGURE 6
RETURN LOSS - SM16LC12**



APPLICATION NOTE

The SM16LC & SM16LCxxC Series are TVS arrays designed to protect I/O or data lines from the damaging effects of ESD, EFT and other types of surges. This product series provides both unidirectional and bidirectional protection, with a surge capability of 500 Watts P_{pp} per line for an 8/20 μ s waveform and ESD protection > 40kV.

BIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)

Ideal for RS-485 applications, the SM16LCxxC Series provides up to eight (8) lines of protection in a common-mode configuration as depicted in Figure 1. This low capacitance series allows the transceiver or telecommunications circuit to operate safely without significant signal distortion.

Circuit connectivity is as follows:

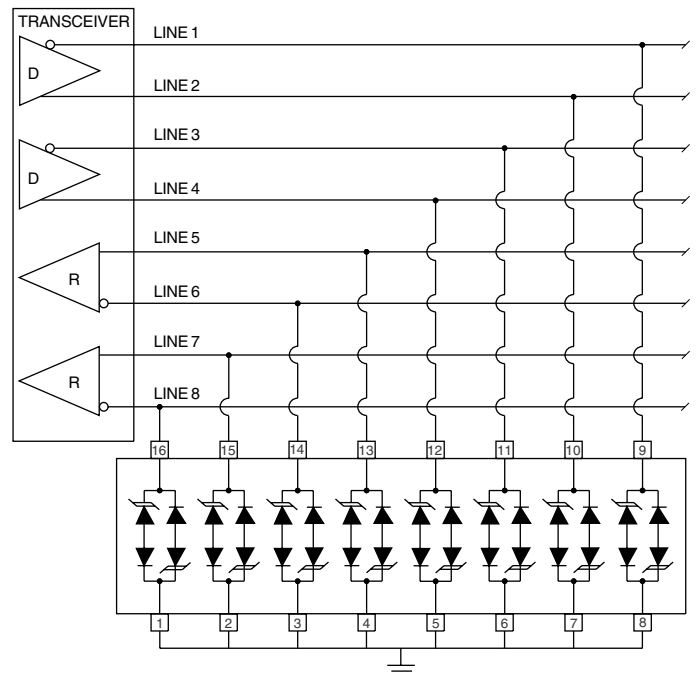
- ✓ Lines 1 is connected to Pin 9.
- ✓ Line 2 is connected to Pin 10.
- ✓ Line 3 is connected to Pin 11.
- ✓ Line 4 is connected to Pin 12.
- ✓ Line 5 is connected to Pin 13.
- ✓ Line 6 is connected to Pin 14.
- ✓ Line 7 is connected to Pin 15.
- ✓ Line 8 is connected to Pin 16.
- ✓ Pins 1-8 are connected to ground.

CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

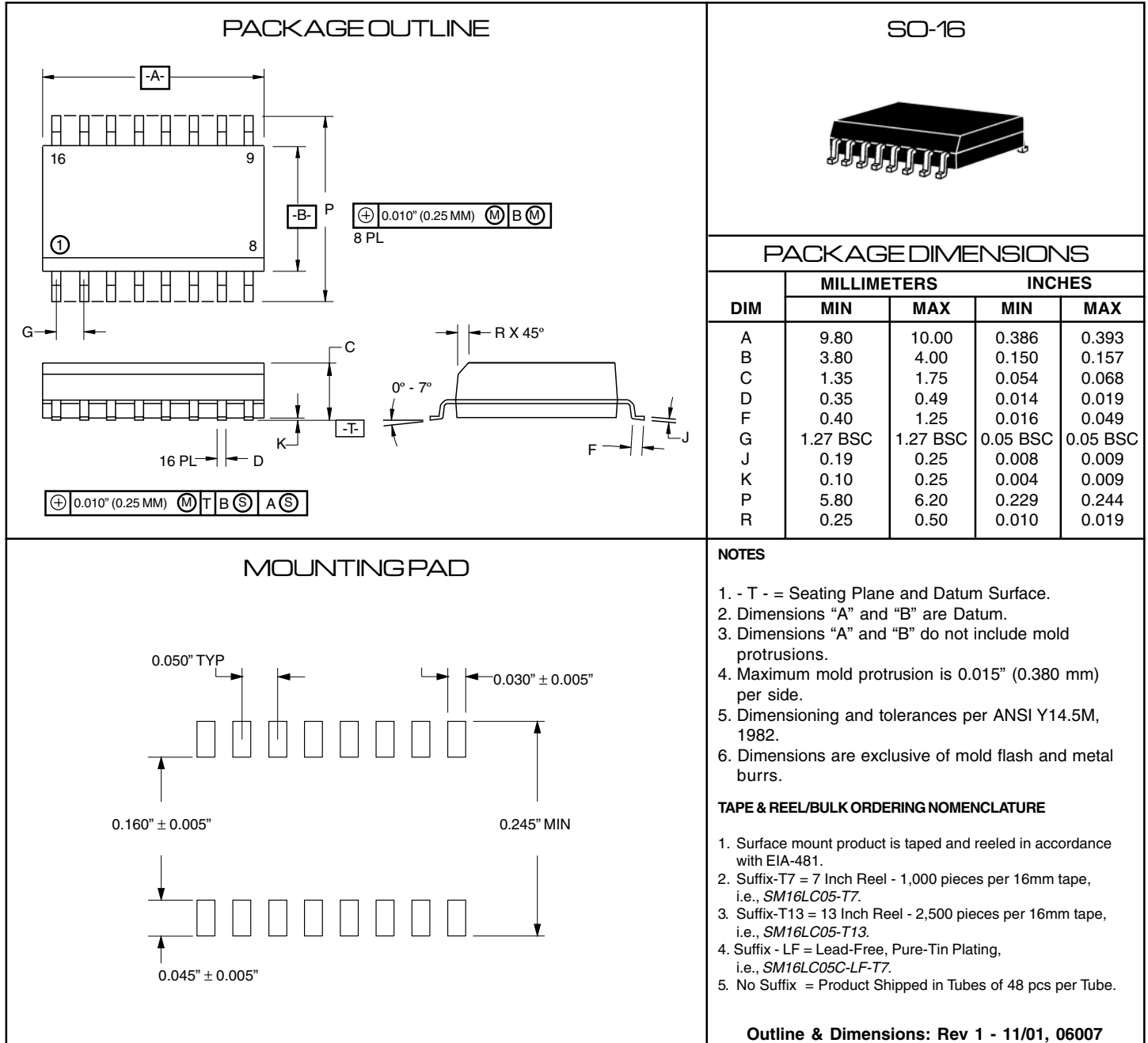
- ✓ The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- ✓ All conductive loops including power and ground loops should be minimized.
- ✓ The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✓ Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

Figure 1. Bidirectional Common-Mode Protection



SM16LC03 thru SM16LC36C

PACKAGE OUTLINE & DIMENSIONS



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